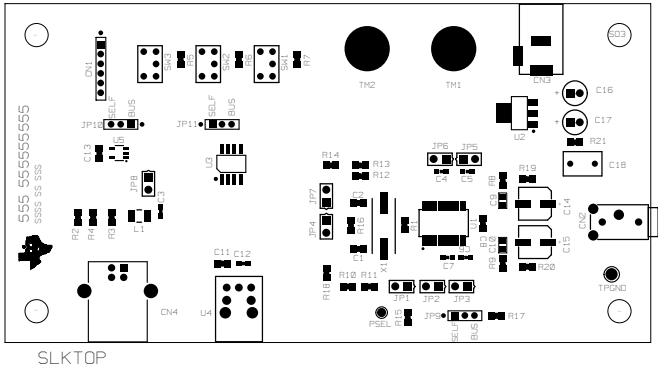
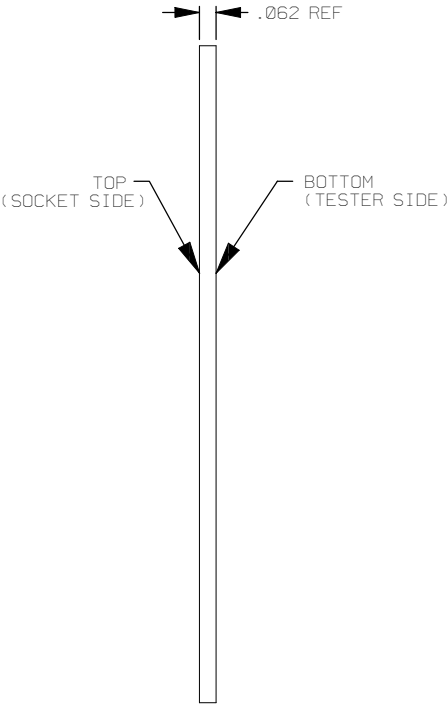


SYM	REVISIONS
A	

- NOTES:
1. ASSEMBLE PER BILL OF MATERIALS
 2. CLEAN BOARD PER EXISTING PROCEDURES
 3. SOLDERING AND WORKMANSHIP SHOULD BE DONE PER IPC-A-610B, CLASS 2
 4. USE WATER SOLUBLE ORGANIC FLUX CORE SOLDER
 5. INSPECT BOARD PER EXISTING QC PROCEDURES



TOP SIDE SHOWN



SIDE VIEW

MATERIAL: SEE BILL OF MATERIALS		PROCESSES: — / —		NEXT ASSEMBLY	
TOLERANCES UNLESS OTHERWISE SPECIFIED				SURFACE ROUGHNESS	
LINEAR		MISCELLANEOUS		THIRD ANGLE PROJECTION	
MILLIMETERS .XX +/- .25 .X +/- .50		INCHES .XXX +/- .010 .XX +/- .020			
HOLES		ANGLES +/- 1° AXIS OF TAPPED HOLES 90° +/- 1° REMOVE ALL BURRS & SHARP EDGES			
MILLIMETERS .XXX +/- .075 .XX +/- .127		INCHES .XXX +/- .003 .XX +/- .005			
DRAFTSMAN: DM/OSG		DATE 03/09/11		TEXAS INSTRUMENTS INC. SEMICONDUCTOR OPERATIONS	
DESIGNER: DM/OSG		DATE 03/09/11		CODE IDENTITY NUMBER 01295	
CHECKER: DM/OSG		DATE 03/09/11		TITLE: ASSEMBLY	
ENGINEER: D. HARTL		DATE 03/09/11		PCM2704/2705 EVM	
APPROVED: D. HARTL		DATE 03/09/11			
RELEASED: MIKE KORSON		DATE 03/09/11			
SCALE N		C SIZE		NA A REV 1 2	